



PDN-06092017-DCSG-01

Product Discontinuation Notification

Issue Date: June 9, 2017

Dear valued customer:

Please be advised that due to change in our assembly vendor's bumping flow, we will be discontinuing products listed in this notification. However, we are offering fully compatible replacement for all the device impacted by this notification.

Our assembly vendor will move from Bump Printing process to Lead Free Bump Plating process. Moving to new process (bump plating) will make replacement devices fully Lead Free (Green). This change from printing to full lead free plating has no risk to customers as no change is being made to Die silicon, substrate design and solder ball metallurgy.

Parts Affected:

See the list of impacted devices/products below:

Current Device#	Replacement Device#
PEX8636-AA50RBC F	PEX8636-AA50RBC G
PEX8664-AA50RBC F	PEX8664-AA50RBC G
PEX8680-AA50RBC F	PEX8680-AA50RBC G
PEX8612-BB50RBC F	PEX8612-BB50RBC G
PEX8616-BB50RBC F	PEX8616-BB50RBC G
PEX8624-BB50RBC F	PEX8624-BB50RBC G
PEX8624-BB50RBI F	PEX8624-BB50RBI G
PEX8632-BB50RBC F	PEX8632-BB50RBC G
PEX8648-BB50RBC F	PEX8648-BB50RBC G
PEX8648-BB50RBI F	PEX8648-BB50RBI G
PEX8649-AA50RBC F	PEX8649-AA50RBC G (see note)
PEX8696-AA50RBC F	PEX8696-AA50RBC G (see note)

Note: "PEX8649-AA50RBC G" & "PEX8696-AA50RBC G" devices already exist

Reason for this change:

This change is driven by change in environmental laws in many countries, customers' desire to move to full lead-free compliance and leaded processes going obsolete/underutilized.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

Device fit, form, function and quality of the product will not be affected by this change. The device specification will remain the same, which will ensure product electrical and functional performance remains the same.

Broadcom has favorable reference reliability data of products using the same process. No adverse reliability and performance is expected.

Effective Dates:

Ordering and Shipments	Dates
Last time order/buy (LTB) with current part #s	September 8, 2017
Current parts (printing process) production stops	December 30, 2017
Last time ship (LTS) for current part #s with printing process	March 30, 2018
New replacement part #s with full lead-free plating process shipment start	March 1, 2018

Sample Availability:

Upon request – Request must be made by June-30, 2017.

Product Comparison:

The table below provides a material property comparison:

Process Factor	Printing - Present	Plating - New
Bumping		
Pl material	Nil	HD4000E
Solder type	Solder paste (Eutectic)	Plating solution (ULA-LF)
Bump UBM	Ti/NiV/Cu	Ti/Cu/Ni
Bump composition	Sn/Pb	Sn1.8Ag
Assembly		
Underfill	UA03	UA32
Chip attach flux	WF-6070	WF-6400
Substrate		
Substrate PreSolder (Bump)	Pb-Sn	SAC SOP

These changes have been reviewed and approved by Broadcom Limited engineers and managers per Broadcom Limited procedure: Change Control and Customer Notification, A-5962-6052-80.

Please contact your Broadcom Limited field sales engineer or Contact Center (<http://www.broadcom.com/contact/>) for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.